LEADING THE SMART FUTURE

SEPTEMBER 18-20, 2019 | TaINEX 1 | TAIWAN
Evertech Enterprise

Your best partner,
Evertech Enterprise

Evertech is creating an affluent life for human beings
OVERVIEW
<table>
<thead>
<tr>
<th>Company Name</th>
<th>Evertech Enterprise Co., Ltd.</th>
</tr>
</thead>
<tbody>
<tr>
<td>CEO</td>
<td>Tae Soo, Han</td>
</tr>
<tr>
<td>Establishment</td>
<td>Jan. 5. 2000</td>
</tr>
<tr>
<td>Paid in Capital</td>
<td>2 Million USD</td>
</tr>
<tr>
<td>Employee</td>
<td>48</td>
</tr>
<tr>
<td>Sales Amount</td>
<td>10 Million USD</td>
</tr>
<tr>
<td>Business</td>
<td>Chemical materials for semiconductor, LED &amp; Electronic industry</td>
</tr>
<tr>
<td>Head office &amp; Plant</td>
<td></td>
</tr>
<tr>
<td>Address</td>
<td>7-9, Dongtansandan 2-gil, Hwaseong-city, Gyeonggi-do, 18487, Korea</td>
</tr>
<tr>
<td>Plottage</td>
<td>4,027m²</td>
</tr>
<tr>
<td>Building</td>
<td>3,693m² (3 stories)</td>
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</tbody>
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Incheon Airport
90km (1hr 30ms)

Seoul

Evertech
History

- 2017: Solder flux for wafer bumping
- 2016: Solder flux for SBM & F/C attach
- 2011: LED materials
- 2010: Ag paste epoxy for all kinds of semiconductor package
- 2009: B-stage epoxy for BOC of memory DRAM

Additional Events:
- 2018.8: Acquired IATF16949
- 2009.9: Acquired ISO/TS 16949
- 2006.12: Acquired ISO9001 & ISO14001

LN2 Piping system for Memory cold test
More than 30 customers: ASE, Amkor, JCET
Many OSAT...
Our Strength

Evertech Enterprise's DNA

- Water Soluble Flux
- Solvent Clean Flux
- No Clean Flux
- Solder Paste

- Conductive D/A
- Non-Conductive D/A
- B-stage Adhesive
- Hybrid Adhesive
- Sintering Paste
- Underfill

- Silicone D/A
- LED Encapsulant
- White Silicone
- TIM Paste

All kinds of materials for Bonding and jointing
- Epoxy & Hybrid
- Silicone & Hybrid
- Solder Flux
Product Line-up
Solder flux

Wafer Bumping
- Water soluble
- Solvent soluble

Flip Chip Attach
- Water soluble
- No clean

Solder Ball Mounting
- Water soluble

Low flux overflow
Minimize flux loss

Uniform bump formation
Excellent cleanability

Various application

Excellent solder joint & Cleanability
(SBM & FC attach)
Epoxy & Hybrid die attach adhesive

**AP4300**: Satisfied AEC-Q100/Q006 (Grade 0 / Grade 1)

**HE-SP-2 (B-stage)**: 10 years for DRAM (BOC)

**BOC**
- AP2500
- AP2510
- A505

**QFN QFP**
- AP4400
- AP4400N

**SOP SOT**
- AP4200
- AP4300
- AP8400H

**BGA**
- AP4700
- AP8310

**Power PKG**

AP4700, AP8310: Hybrid adhesive, Good MRT performance
LED Materials (White Silicone)

White Silicone (WS4030 / WS4030A)

Silicone Encapsulant

Silicone Die Attach Adhesive

Epoxy & Hybrid

Die attach adhesive (Silver)

<Reflectivity @ 450nm>

97%
98%
99%
100%

Conventional

WS4030

Improved 1% of “Im/W”
LED Materials (Encapsulant & D/A Adhesive)

- White Silicone
- Epoxy & Hybrid Die Attach Adhesive (Silver)
  - AP2400
  - AP2510
  - AP2600

Silicone Encapsulant (EC4506C/EC4507)
Silicone Die Attach Adhesive (CL5610)

<table>
<thead>
<tr>
<th>Chip (Die) damage</th>
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<tbody>
<tr>
<td>Pad shape (Before curing) 50x</td>
</tr>
<tr>
<td>pad shape (After curing) 50x</td>
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</tbody>
</table>

Ref' CL5610

Low fume!
Future works

TIM & Sintering paste
High thermal conductive paste

When bond line controls, Die crack problem occurs

High Thermal Conductive paste
Application: Power IC, SOIC, SiP, MOSFET
Target: High Thermal conductivity (>10W/mK)
High DST, Low Volume Resistivity
Under Developing: ~2020年5月

Sintering Paste
Application: Power IC, RF module
Target: Low Curing Temp.,
High Thermal Conductivity (>100W/mK)
Under Developing: ~2020年12月
Thank you!